

FORM PTO-1449

LIST OF PATENTS AND PUBLICATIONS FOR
APPLICANT'S INFORMATION DISCLOSURE
STATEMENT

(Use several sheets if necessary)

ATTY. DOCKET NO.

10007343

APPLICATION NO.

CONFIRMATION NO.

APPLICANT

Laurie S. MITTELSTADT

FILING DATE

July 31, 2001

GROUP

1756

1000 U.S. PRO

09/917650

07/31/01

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
JA	1A	6,077,644	6/20/2000	Hada, et al.	430	270.1
JA	1B	5,894,058	4/13/1999	Hatakeyama, et al.	430	313
JA	1C	4,773,750	9/27/1988	Bruning	353	122
	1D					
	1E					
	1F					
	1G					
	1H					
	1I					
	1J					
	1K					

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	TRANSLATION	
							YES	NO
	1L							
	1M							
	1N							
	1O							
	1P							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

JA	1Q	J. F. Kuhmann, et al., "THROUGH WAFER INTERCONNECTS AND FLIP-CHIP BONDING: A TOOLBOX FOR ADVANCED HYBRID TECHNOLOGIES FOR MEMS", Eurosensors XIII, 13th, European conference on Solid-State transducers [Mittelstadt, Laurie], pp. 265-72, September 12-15, 1999.
JA	1R	Matthias HESCHEL, et al., "CONFORMAL COATING BY PHOTORESIST OF SHARP CORNERS OF ANISOTROPICALLY ETCHED THROUGH-HOLES IN SILICON", Sensors and Actuators A 70, October 1, 1998, pp. 75-80.
JA	1S	V.G. KUTCHOUKOV, et al., "NEW PHOTORESIST COATING METHOD FOR 3-D STRUCTURED WAFERS", Sensors and Actuators 85 (2000) August 25, 2000, pp. 377-383.

EXAMINER

John McPherson

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JA	1Q	R. SCHNUPP, et al., "ELECTRODEPOSITION OF PHOTORESIST: OPTIMIZATION OF DEPOSITION CONDITIONS, INVESTIGATION OF LITHOGRAPHIC PROCESSES AND CHEMICAL RESISTANCE", Sensors and Actuators 85 (2000) August 25, 2000, pp. 310-315.
	1R	
	1S	

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